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| | | H11A.U/14 ## | |
|---|---|---|--|
| To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. | | | |
| 1. Name of Con | eveying Party(ies): | 2. Name and Address of Receiving Party(ies): | |
| (1) ATSUKO YAMAGUCHI (2) HIROSHI FUKUDA (3) HIROKI KAWADA (4) TATSUYA MAEDA | | Name: Hitachi High-Technologies Corporation Address: 24-14, Nishishinbashi 1-chome, City: Minato-ku, Tokyo, Japan | |
| Additional names of conveying parties attached: ☐ Yes ☒ No | | | |
| 3. Nature of Conveyance: | | 1 | |
| | • | | |
| ☑ Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name ☐ Other: Execution Date: (1) May 27, 2005 (2) May 30, 2005 | | | |
| (3)(4) May 2 | | | |
| 4. (a) Patent At | oplication Number(s): | | |
| If this document is being filed together with a new application, the execution date of the application is: | | 4. (b) Patent Numbers: | |
| Additional Numbers Attached. □ Yes ☒ No | | | |
| 5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed: | | 6. Total Number of Applications and Patents Involved: 1 | |
| Name: | Stanley P. Fisher | 7. Total Fee: \$40.00 (37 C.F.R. § 3.41) | |
| Address: | Reed Smith LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, Va. 22042 | ☑ Enclosed. ☑ Authorized to be charged to deposit account. | |
| | | 8. Deposit Account Number: 08-1480 | |
| | | ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT | |
| DO NOT USE T | HIS SPACE | | |
| 9. Statement and Signature: | | | |
| To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document. | | | |
| | All - | JULY 21, 2005 | |
| Stanley P. Fisher, Registration No. 24, 344 | | Juan Carlos A. Marquez, Registration No. 34,072 | |
| | | | |
| Total number of | pages comprising cover sheet: 1 | | |

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PATENT REEL: 016802 FRAME: 0721

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan,

located at 24-14, Nishishinbashi 1-chome, Minato-ku, Tokyo, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

EVALUATION METHOD OF FINE PATTERN FEATURE, ITS EQUIPMENT, AND METHOD OF SEMICONDUCTOR DEVICE FABRICATION

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted.

to be held and enjoyed by said Hitachi High-Technologies Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

RECORDED: 07/21/2005

| INVENTOR(S) (発明者フルネームサイン) | Date Signed (署名日) |
|------------------------------|----------------------|
| 1) Atsuko Yamaguchi | 5/27/2005 |
| 2) Idvishi Fulcada | 5/30/2005 |
| 3) Hirohi Kawada | 5/25/2005 |
| 4) Tatsuzo maeda | 5/25/2005 |
| 5) | |
| 6) | |
| 7) | |
| 8) | |
| 9) | |
| 10) | |
| | |

PATENT REEL: 016802 FRAME: 0722